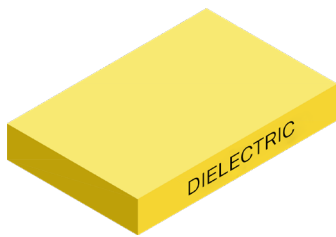


BOND SHEET HTG 3,2W Tg 180°C Low CTE

STANDARD CONSTRUCTION



Isolation thickness μm (mils)
 70 (2,8) 80 (3,1) 100 (3,9)
Dielectric thickness tolerance
 + 10 μm (+/- 0,4 mils)

*Other constructions available upon request

DESCRIPTION

High Tg - B-stage dielectric prepreg glass reinforced with high thermal conductivity. It is based on epoxy ceramic chemistry, and intended for effective bonding between multilayer circuits (PCB) and metal heat spreaders. Its high dielectric strength and resistance to thermal shocks added to its high thermal conductivity assures effective heat dissipation in critical power circuitry. Its low CTE value is ideal to achieve excellent interconnect reliability over thermal cycles.



UL Approved QMITS2
 File: E47820
 IPC-4101



RoHS 3 / REACH
 Last updated compliance directive



PROPERTIES	GUARANTEED VALUES			UNITS	TOLERANCE
	A	B	C		
Nominal thickness (pressed)	70 (2,8)	80 (3,15)	100 (4,0)	μm (mils)	+/- 10 μm (0,4mils)
Area weight	145 (203)	185 (259)	225 (315)	g/m^2 (Lb/mils ²)	+/- 10 g/m^2 (14 Lb/mils ²)
Glass fabric 106	24,4 (34,8)	24,4 (34,8)	-	g/m^2 (Lb/mils ²)	+/- 1,0 g/m^2 (1,4 Lb/mils ²)
Glass fabric 1078	-	-	46,8 (66,4)	g/m^2 (Lb/mils ²)	+/- 2,0 g/m^2 (2,8 Lb/mils ²)
Prepreg shelf life (see storage recommendations)	3	3	3	months	-

PREPREG once applied (1)	VALUES	UNITS	TEST METHOD
Time to blister at 288°C, floating solder bath	60	sec	IEC-61189
Copper Peel strength Cu70 μm (2oz)	>1,0 (>5,7)	N/mm (Lb/in)	IPC-TM 650-2.4.8
Thermal conductivity (resin)	3,00 (0,076)	W/mK (W/inK)	ASTM D5470
Comparative tracking index (CTI)	≥ 600	V	IEC-61112
Thermal impedance (dielectric layer) HTC 70 μm	0,23 (0,036)**	Kcm^2/W (Kin^2/W)	ASTM D5470
Thermal impedance (dielectric layer) HTC 80 μm	0,27 (0,042)**	Kcm^2/W (Kin^2/W)	ASTM D5470
Thermal impedance (dielectric layer) HTC 100 μm	0,33 (0,051)**	Kcm^2/W (Kin^2/W)	ASTM D5470
Dielectric breakdown voltage, (AC)	≥ 4	kV/100 μm dielectric layer	IPC TM 650 2.5.6.3
Flammability, according UL-94, class	V-0	class	UL-94
Glass transition temperature of dielectric layer (byTMA)	>180	°C	IPC-TM 650-2.4.24
Decomposition Temperature (Td) Initial	340	°C	IPC-TM 650-2.3.41
Decomposition Temperature (Td) 5% loss	420	°C	IPC-TM 650-2.3.41
Thermal delamination (Td) T 260	>80	min	IPC-TM 650-2.4.24.1
Thermal delamination (Td) T 288	>80	min	IPC-TM 650-2.4.24.1
Thermal delamination (Td) T 300	>80	min	IPC-TM 650-2.4.24.1
CTE (x,y)	14-15	ppm/°C	IPC-TM 650-2.4.41
CTE (z) <Tg	37	ppm/°C	IPC-TM 650-2.4.24
CTE (z) >Tg	172	ppm/°C	IPC-TM 650-2.4.24
Z-axis Expansion (50-250°C)	1.8 (77ppm)	%	IPC-TM 650-2.4.24

(1) Pressed under vacuum, temperature and pressure (see cycle below), between thick aluminium sheet (alloy 5052), and ED copper foil 70 μm
 (**) Thermal Conductivity and Impedance values may have a +/- 15% deviation.

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DELIVERY FORM

In cut to size sheets upon request.

PROCESS RECOMMENDATIONS**PREPREG STORAGE**

Store preferably in the original unopened package or sealed by tape. Keep storage climate conditions below 24°C and 55% relative humidity. In the event of storing under very low warehouse temperatures give some time for the packed prepreg to stabilize to room temperature before opening. Keeping the above mentioned storage conditions and avoiding prepreg damage by humidity uptake will give a useful life of 3 months after production date.

PRESS CYCLE

Resin and prepreg parameters have been adjusted for low flow performance. This means they are suitable for heating rates around 3 to 7°C/min, and specific pressures between 18-22 bars. Vacuum applied during press cycle is mandatory for optimal performance. Use of synthetic thermal resistance pads should be test choice. Curing temperature cycle is 1 hour of material temperature over 190°C.

METAL SURFACE PREPARATION

Aluminium is supplied with mechanical treatment and special primer in order to guarantee the correct adherence in the ML process.

The data is based on typical values of standard production and should be considered as general information. Our company reserves the right to future changes. It is the responsibility of the user to ensure that the product complies with his requirements.